

Features

- Epitaxial Planar Die Construction
- Ideally Suited for Automated Assembly Processes
- Ideal for Medium Power Switching or Amplification Applications
- Complementary NPN Type Available (2DC4672)
- **Lead Free, RoHS Compliant (Note 1)**
- **Halogen and Antimony Free, "Green" Device (Note 2)**
- **Qualified to AEC-Q101 Standards for High Reliability**

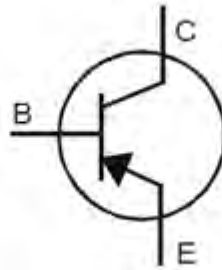
Mechanical Data

- Case: SOT89
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish — Matte Tin. Solderable per MIL-STD-202, Method 208
- Weight: 0.052 grams (approximate)

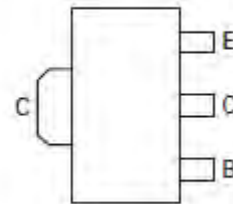
SOT89



Top View



Device symbol



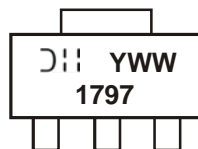
Pin-out Top

Ordering Information (Note 3 & 4)

Part Number	Grade	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
2DA1797-13	Commercial	1797	13	12	2500
2DA1797Q-13	Automotive	1797	13	12	2500

- Notes:
1. No purposefully added lead.
 2. Halogen and Antimony Free. Diodes Inc's "Green" Policy can be found on our website at <http://www.diodes.com>
 3. For packaging details, go to our website at <http://www.diodes.com>
 4. Products with Q-suffix are automotive grade. Automotive products are electrical and thermal the same as the commercial, except where specified.

Marking Information



1797 = Product Type Marking Code
 YWW = Date Code Marking
 Y = Last digit of year (ex: 8 = 2008)
 WW = Week code (01 – 53)

Maximum Ratings @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V _{CBO}	-50	V
Collector-Emitter Voltage	V _{CEO}	-50	V
Emitter-Base Voltage	V _{EBO}	-6	V
Peak Pulse Current	I _{CM}	-6	A
Continuous Collector Current	I _C	-3	A

Thermal Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P _D	0.9	W
Thermal Resistance, Junction to Ambient Air (Note 5)	R _{θJA}	139	°C/W
Power Dissipation (Note 6)	P _D	2	W
Thermal Resistance, Junction to Ambient Air (Note 6)	R _{θJA}	62.5	°C/W
Thermal Resistance, Junction to Leads (Note 7)	R _{θJA}	5.3	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Conditions
OFF CHARACTERISTICS						
Collector-Base Breakdown Voltage	BV _{CBO}	-50	—	—	V	I _C = -50μA, I _E = 0
Collector-Emitter Breakdown Voltage (Note 8)	BV _{CEO}	-50	—	—	V	I _C = -1mA, I _B = 0
Emitter-Base Breakdown Voltage	BV _{EBO}	-6	—	—	V	I _E = -50μA, I _C = 0
Collector Cut-Off Current	I _{CBO}	—	—	-0.1	μA	V _{CB} = -50V, I _E = 0
Emitter Cut-Off Current	I _{EBO}	—	—	-0.1	μA	V _{EB} = -5V, I _C = 0
ON CHARACTERISTICS (Note 8)						
Collector-Emitter Saturation Voltage	V _{CE(sat)}	—	-100	-350	mV	I _C = -1A, I _B = -50mA
DC Current Gain	h _{FE}	82	—	270	—	V _{CE} = -2V, I _C = -500mA
SMALL SIGNAL CHARACTERISTICS						
Output Capacitance	C _{obo}	—	27	—	pF	V _{CB} = -10V, I _E = 0, f = 1MHz
Current Gain-Bandwidth Product	f _T	—	160	—	MHz	V _{CE} = -2V, I _C = -100mA, f = 100MHz

- Notes:
5. Device mounted on FR-4 PCB with minimum recommended pad layout.
 6. Device mounted on FR-4 PCB with 1 inch² copper pad layout.
 7. Thermal resistance from junction to solder-point (at the end of the collector lead).
 8. Measured under pulsed conditions. Pulse width = 300μs. Duty cycle ≤2%.

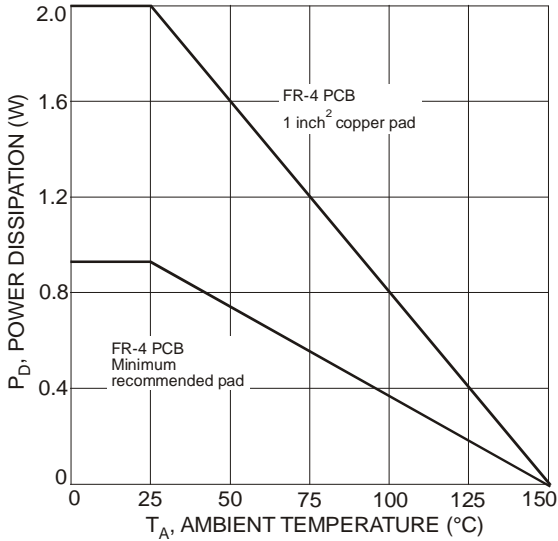


Fig. 1 Power Dissipation vs. Ambient Temperature

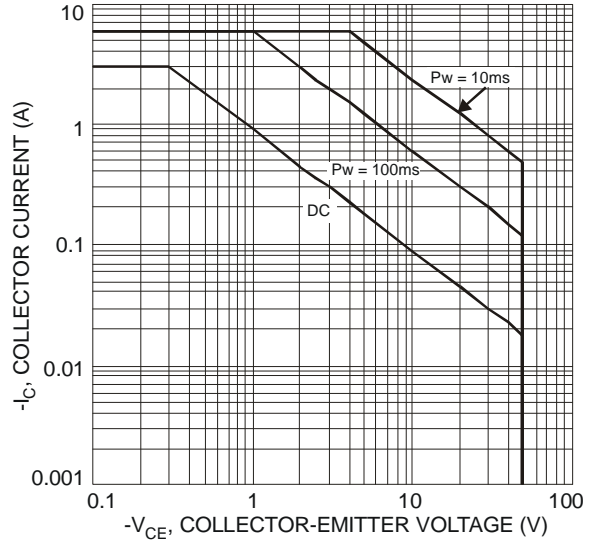


Fig. 2 Typical Collector Current vs. Collector-Emitter Voltage (Note 5)

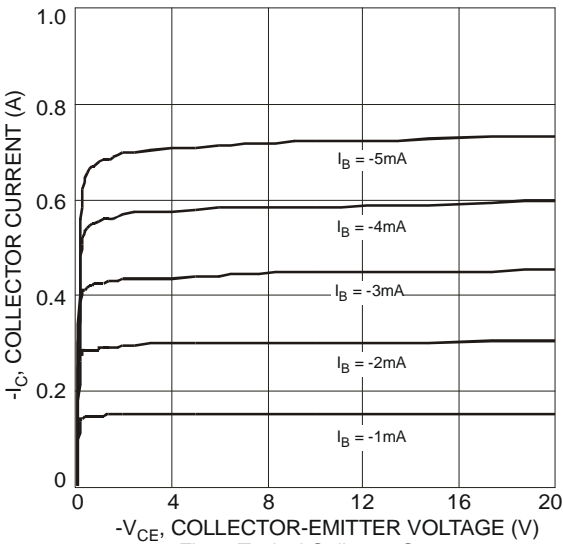


Fig. 3 Typical Collector Current vs. Collector-Emitter Voltage

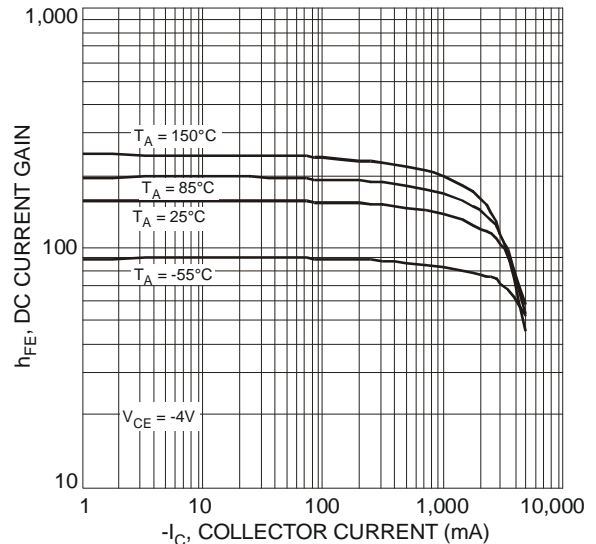


Fig. 4 Typical DC Current Gain vs. Collector Current

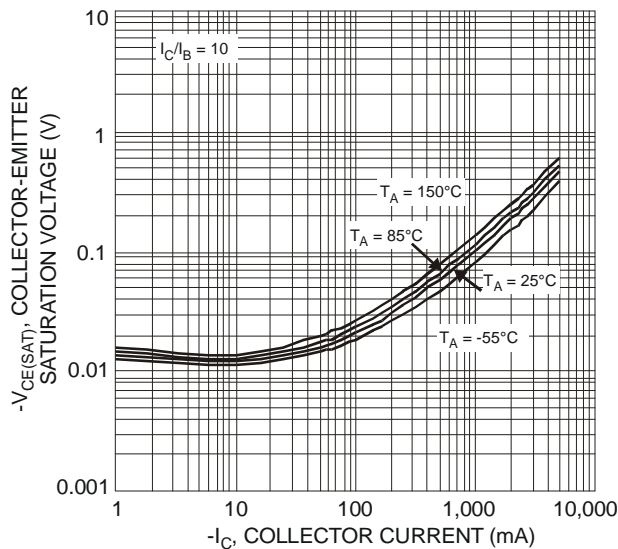


Fig. 5 Typical Collector-Emitter Saturation Voltage vs. Collector Current

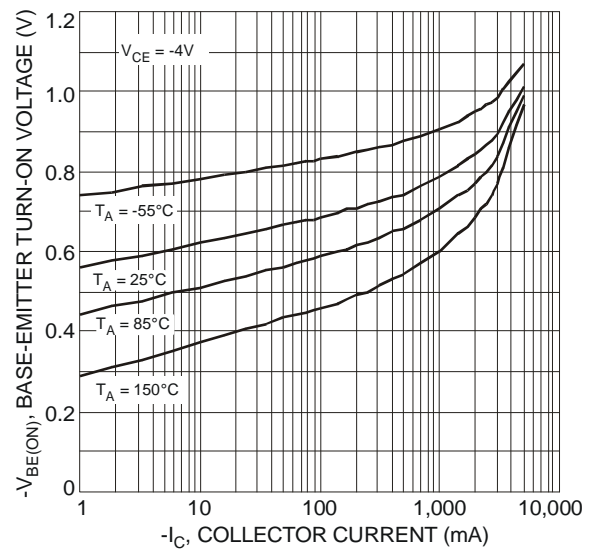


Fig. 6 Typical Base-Emitter Turn-On Voltage vs. Collector Current

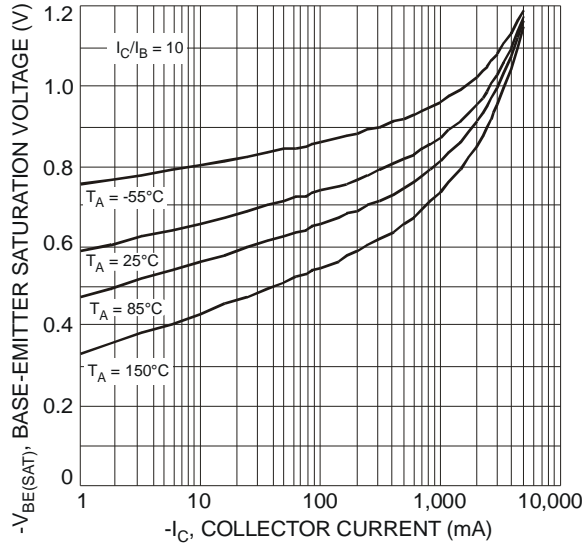


Fig. 7 Typical Base-Emitter Saturation Voltage vs. Collector Current

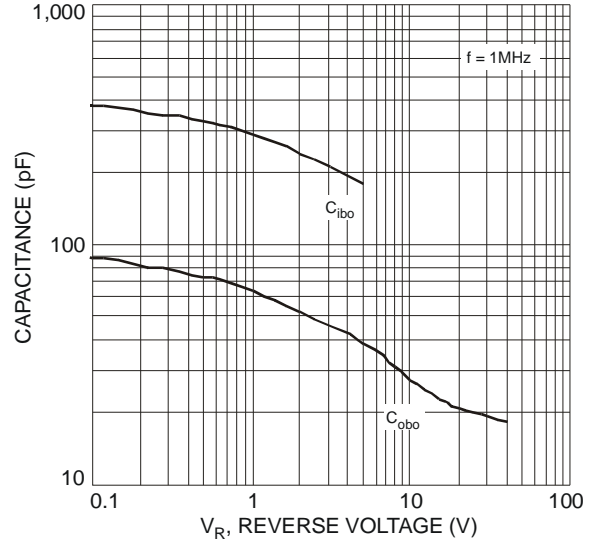


Fig. 8 Typical Capacitance Characteristics

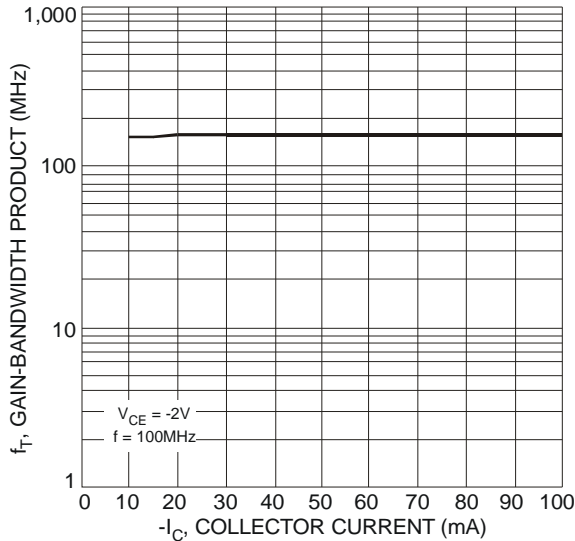


Fig. 9 Typical Gain-Bandwidth Product vs. Collector Current

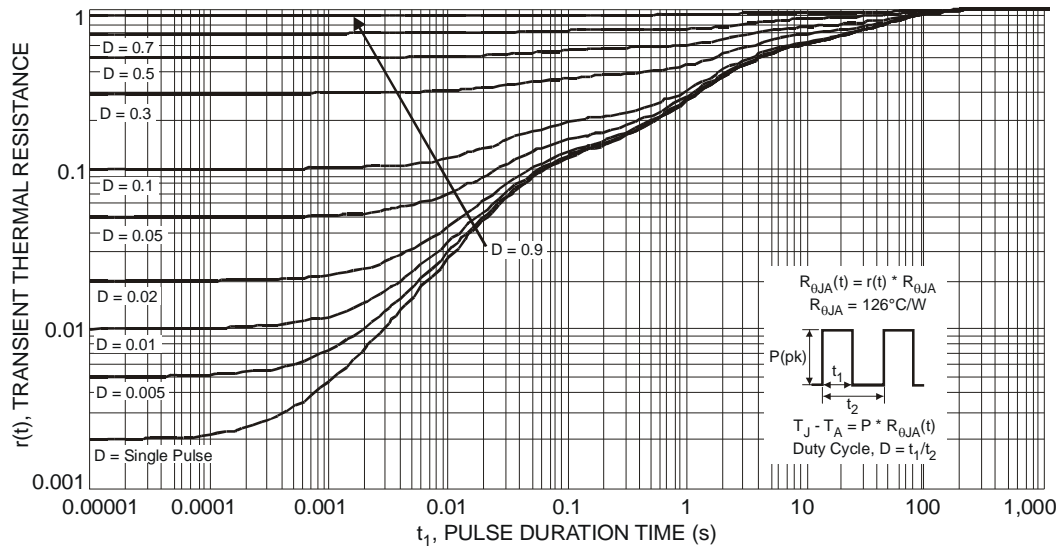
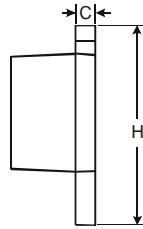
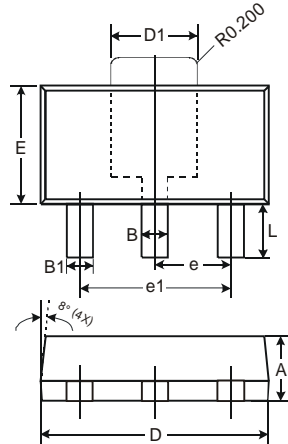


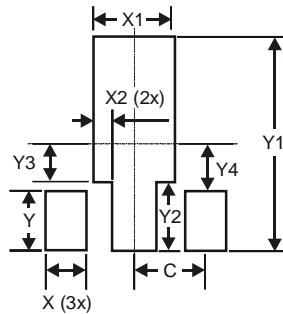
Fig. 10 Transient Thermal Response

Package Outline Dimensions



SOT89		
Dim	Min	Max
A	1.40	1.60
B	0.44	0.62
B1	0.35	0.54
C	0.35	0.43
D	4.40	4.60
D1	1.52	1.83
E	2.29	2.60
e	1.50 Typ	
e1	3.00 Typ	
H	3.94	4.25
L	0.89	1.20
All Dimensions in mm		

Suggested Pad Layout



Dimensions	Value (in mm)
X	0.900
X1	1.733
X2	0.416
Y	1.300
Y1	4.600
Y2	1.475
Y3	0.950
Y4	1.125
C	1.500

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